

ABSTRACT

To provide a printed circuit board, a buildup substrate and a method of manufacturing the printed circuit board capable of curbing a transmission loss thereof at a desired frequency.

A printed circuit board having a multilayer substrate , a via hole penetrating the multilayer substrate, a surface wiring wired on the surface of the multilayer substrate and connected to an end which is one end of the via hole, at least one inner layer wiring formed inside the multilayer substrate and connected to a portion other than upper and lower ends of a conductive part of the via hole, and a current-carrying element connected to an end having no surface wiring connected thereto on an opposite side to the end, and wherein the current-carrying element has an electrical length by which a value of an impedance at a predetermined frequency on seeing the current-carrying element side from a connection point between the inner layer wiring and the via hole closest to the end is larger than a value of the impedance on seeing the end from the connection point in the case where the current-carrying element is nonexistent.